



# SMT Power Inductors

**Series/Type: B82479G1**

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B82479G1684M000		2020-05-29	2020-11-30	2021-05-31
B82479G1683M000		2020-05-29	2020-11-30	2021-05-31
B82479G1474M000		2020-05-29	2020-11-30	2021-05-31



Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B82479G1473M000		2020-05-29	2020-11-30	2021-05-31
B82479G1334M000		2020-05-29	2020-11-30	2021-05-31
B82479G1333M000		2020-05-29	2020-11-30	2021-05-31
B82479G1224M000		2020-05-29	2020-11-30	2021-05-31
B82479G1223M000		2020-05-29	2020-11-30	2021-05-31
B82479G1154M000		2020-05-29	2020-11-30	2021-05-31
B82479G1153M000		2020-05-29	2020-11-30	2021-05-31
B82479G1105M000		2020-05-29	2020-11-30	2021-05-31
B82479G1104M000		2020-05-29	2020-11-30	2021-05-31
B82479G1103M000		2020-05-29	2020-11-30	2021-05-31

Please contact your nearest TDK sales office if you need support in selecting a suitable substitute. The addresses of our worldwide sales network are presented at [www.tdk-electronics.tdk.com/sales](http://www.tdk-electronics.tdk.com/sales).

### SMD

**Rated inductance 10 ... 1000  $\mu$ H**

**Rated current 0.53 ... 3.9 A**



#### Construction

- Ferrite core
- Magnetically shielded
- Winding: enamel copper wire
- Winding soldered to terminals
- Plastic terminal carrier

#### Features

- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- RoHS-compatible

#### Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Telecommunications
- Industrial electronics

#### Terminals

- Base material CuSn6P
- Layer composition Ni, Sn (lead-free)
- Electro-plated

#### Marking

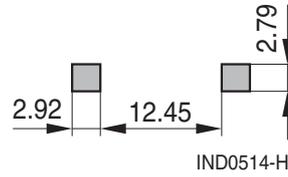
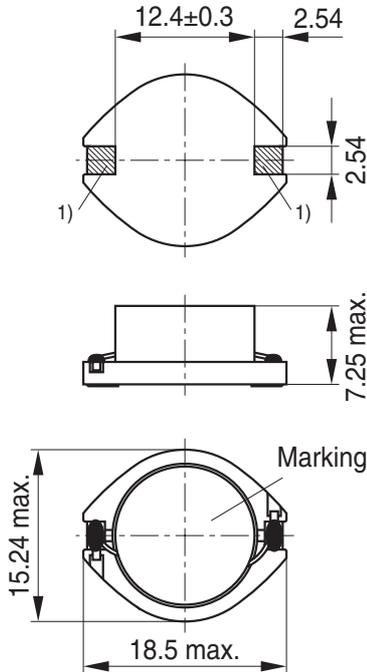
- Marking on component:  
Manufacturer, L value ( $\mu$ H, coded),  
manufacturing date (YWWD)
- Minimum data on reel:  
Manufacturer, ordering code, L value,  
quantity, date of packing

#### Delivery mode and packing unit

- 32-mm blister tape, wound on 330-mm  $\varnothing$  reel
- Packing unit: 250 pcs./reel

**SMD**

**Dimensional drawing and layout recommendation**



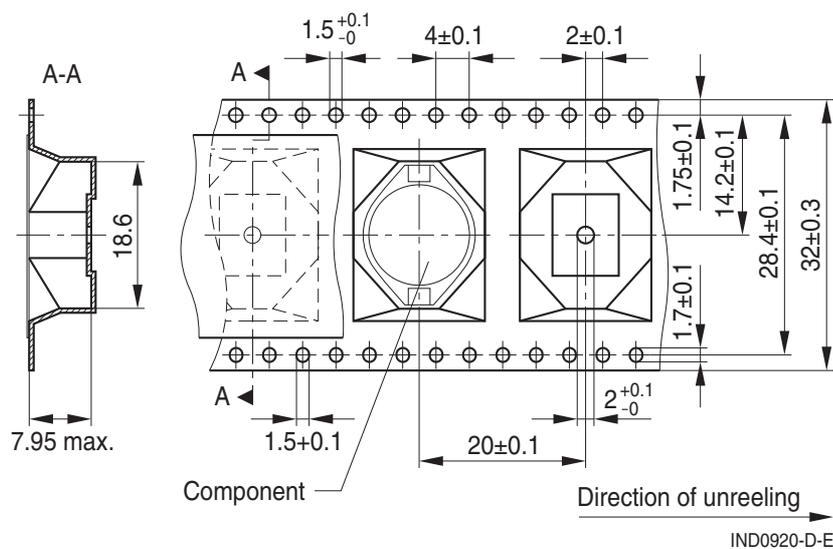
Dimensions in mm

Component tolerances  $\pm 0.2$  mm unless otherwise noted.

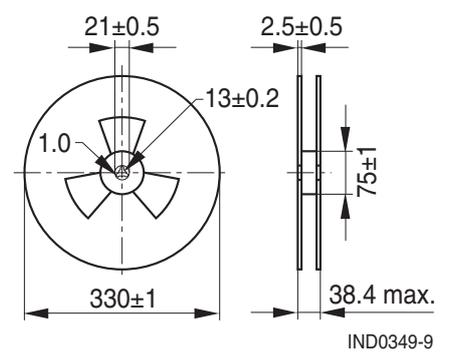
IND0494-Q-E

**Taping and packing**

**Blister tape**



**Reel**



Dimensions in mm

**SMD**
**Technical data and measuring conditions**

Rated inductance $L_R$	Measured with LCR meter Agilent 4284A at frequency $f_L$ , 0.1 V, +20 °C
Rated temperature $T_R$	+85 °C
Rated current $I_R$	Max. permissible DC with temperature increase of $\leq 40$ K at rated temperature
Saturation current $I_{sat}$	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%
DC resistance $R_{max}$	Measured at +20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (5 ±0.3) s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD 020D)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C ... +150 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 4.2 g

**Characteristics and ordering codes**

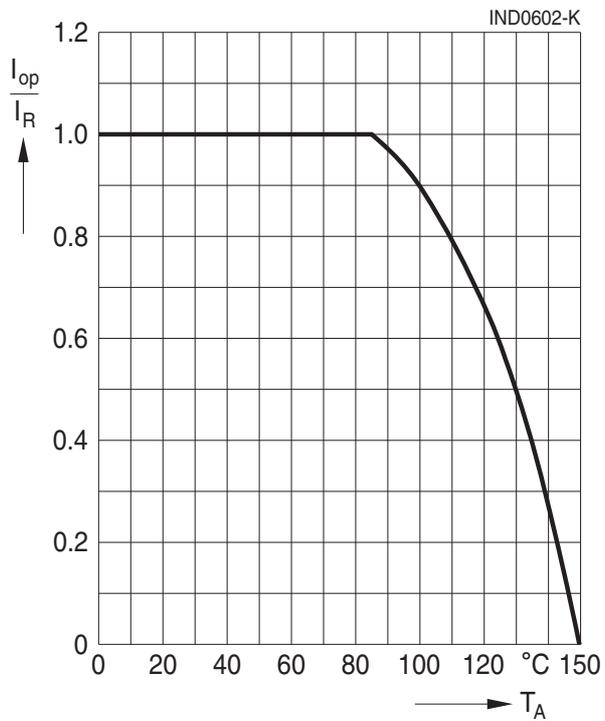
$L_R$ $\mu\text{H}$	Tolerance	$f_L$ MHz	$I_R$ A	$I_{sat}$ A	$R_{max}$ $\Omega$	Ordering code
10	$\pm 20\% \triangleq M$	0.1	3.90	8.00	0.040	B82479G1103M000
15		0.1	3.40	7.00	0.048	B82479G1153M000
22		0.1	3.10	6.00	0.059	B82479G1223M000
33		0.1	2.80	5.00	0.075	B82479G1333M000
47		0.1	2.40	4.00	0.097	B82479G1473M000
68		0.1	2.00	3.00	0.138	B82479G1683M000
100		0.1	1.70	2.40	0.207	B82479G1104M000
150		0.1	1.30	2.10	0.293	B82479G1154M000
220		0.1	1.10	1.90	0.47	B82479G1224M000
330		0.1	0.86	1.20	0.78	B82479G1334M000
470		0.1	0.73	1.10	1.08	B82479G1474M000
680		0.1	0.64	0.96	1.40	B82479G1684M000
1000		0.1	0.53	0.80	2.01	B82479G1105M000

Sample kit available. Ordering code: B8247XX001

For more information refer to chapter "Sample kits".

**SMD**

**Current derating  $I_{op}/I_R$   
versus ambient temperature  $T_A$**   
(rated temperature  $T_R = +85\text{ °C}$ )



## Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.  
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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The following applies to all products named in this publication:

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